

Preferred Device

Small Signal MOSFET 250 mAmps, 200 Volts, Logic Level

N-Channel TO-92

This MOSFET is designed for high voltage, high speed switching applications such as line drivers, relay drivers, CMOS logic, microprocessor or TTL to high voltage interface and high voltage display drivers.

Features

- Low Drive Requirement, $V_{GS} = 3.0 \text{ V}$ max
- Inherent Current Sharing Capability Permits Easy Paralleling of many Devices
- Pb–Free Packages are Available*

MAXIMUM RATINGS

| Rating | Symbol | Value | Unit |
|--|-----------------------------------|-------------|-------------|
| Drain-Source Voltage | V _{DSS} | 200 | Vdc |
| Gate-Source Voltage | V _{GS} | ±20 | Vdc |
| Drain Current Continuous (Note 1) Pulsed (Note 2) | I _D I _{DM} | 250 500 | mAdc |
| Total Power Dissipation @ $T_A = 25^{\circ}C$ Derate above $T_A = 25^{\circ}C$ | P _D | 350 6.4 | mW mW/°C |
| Operating and Storage Temperature Range | T _J , T _{stg} | -55 to +150 | °C |

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

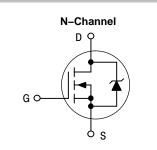
- 1. The Power Dissipation of the package may result in a lower continuous drain current.
- 2. Pulse Test: Pulse Width \leq 300 µs, Duty Cycle \leq 2.0%.

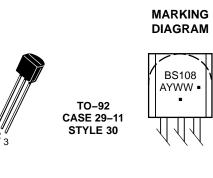


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250 mAMPS 200 VOLTS R_{DS(on)} = 8 Ω





| BS108 | = Device Code |
|-------|---------------------|
| А | = Assembly Location |
| Y | = Year |

- WW = Work Week
 - = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

| Device | Package | Shipping |
|-----------|--------------------|----------------|
| BS108 | TO-92 | 1000 Units/Box |
| BS108G | TO-92 (Pb-Free) | 1000 Units/Box |
| BS108ZL1 | TO-92 | 2000/Ammo Pack |
| BS108ZL1G | TO–92 (Pb–Free) | 2000/Ammo Pack |

*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

Preferred devices are recommended choices for future use and best overall value.

BS108

| Characteristic | Symbol | Min | Тур | Max | Unit |
|---|---------------------|-----|------|-----------|------|
| OFF CHARACTERISTICS | | | | | |
| Drain–Source Breakdown Voltage (V _{GS} = 0, I _D = 10 μA) | V _{(BR)DS} | 200 | _ | | Vdc |
| Zero Gate Voltage Drain Current $(V_{DSS} = 130 \text{ Vdc}, V_{GS} = 0)$ | I _{DSS} | _ | _ | 30 | nAdc |
| Gate-Body Leakage Current ($V_{GS} = 15 \text{ Vdc}, V_{DS} = 0$) | IGSSF | _ | _ | 10 | nAdc |
| ON CHARACTERISTICS (Note 3) | | | | | • |
| Gate Threshold Voltage $(I_D = 1.0 \text{ mA}, V_{DS} = V_{GS})$ | V _{GS(th)} | 0.5 | _ | 1.5 | Vdc |
| Static Drain-to-Source On-Resistance $(V_{GS} = 2.0 \text{ Vdc}, I_D = 50 \text{ mA})$ $(V_{GS} = 2.8 \text{ Vdc}, I_D = 100 \text{ mA})$ | r _{DS(on)} | | | 10 8.0 | Ω |
| Drain Cutoff Current ($V_{GS} = 0.2 \text{ V}, V_{DS} = 70 \text{ V}$) | I _{DSX} | - | _ | 25 | μΑ |
| Forward Transconductance $(I_D = 120 \text{ mA}, V_{DS} = 20 \text{ V})$ | 9 _{FS} | _ | 0.33 | _ | Mhos |
| DYNAMIC CHARACTERISTICS | | | | | • |
| Input Capacitance $(V_{DS} = 25 \text{ V}, V_{GS} = 0, f = 1.0 \text{ MHz})$ | C _{iss} | _ | _ | 150 | pF |
| Output Capacitance (V _{DS} = 25 V, V _{GS} = 0, f = 1.0 MHz) | C _{oss} | _ | _ | 30 | pF |
| Reverse Transfer Capacitance ($V_{DS} = 25 V$, $V_{GS} = 0$, f = 1.0 MHz) | C _{rss} | - | _ | 10 | pF |
| SWITCHING CHARACTERISTICS | • | · | • | | |
| Turn–On Time (See Figure 1) | t _{d(on)} | _ | - | 15 | ns |
| Turn–Off Time (See Figure 1) | t _{d(off)} | - | - | 15 | ns |

3. Pulse Test: Pulse Width \leq 300 µs, Duty Cycle = 2.0%.

RESISTIVE SWITCHING

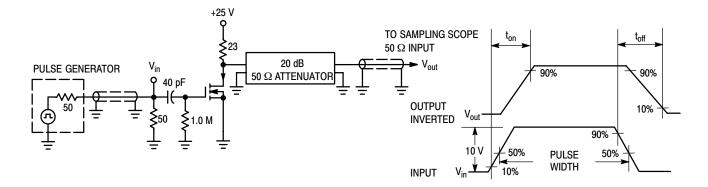
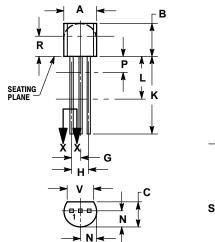


Figure 1. Switching Test Circuit

Figure 2. Switching Waveforms

查询"BS108G"供应商

TO-92 (TO-226) CASE 29-11 **ISSUE AL**







NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI 1. Y14.5M, 1982.
- 2
- TI4-3M, 1962. CONTROLLING DIMENSION: INCH. CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED. LEAD DIMENSION IS UNCONTROLLED IN P AND 3.
- 4. BEYOND DIMENSION K MINIMUM.

| | INC | HES | MILLIN | IETERS |
|-----|-------|-------|--------|--------|
| DIM | MIN | MAX | MIN | MAX |
| Α | 0.175 | 0.205 | 4.45 | 5.20 |
| В | 0.170 | 0.210 | 4.32 | 5.33 |
| С | 0.125 | 0.165 | 3.18 | 4.19 |
| D | 0.016 | 0.021 | 0.407 | 0.533 |
| G | 0.045 | 0.055 | 1.15 | 1.39 |
| Н | 0.095 | 0.105 | 2.42 | 2.66 |
| J | 0.015 | 0.020 | 0.39 | 0.50 |
| Κ | 0.500 | | 12.70 | |
| L | 0.250 | | 6.35 | |
| Ν | 0.080 | 0.105 | 2.04 | 2.66 |
| Ρ | | 0.100 | | 2.54 |
| R | 0.115 | | 2.93 | |
| × | 0.135 | | 3.43 | |

STYLE 30: PIN 1. DRAIN 2. GATE

3. SOURCE

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